

## Photodiode array chip FM034MP.01

### Description

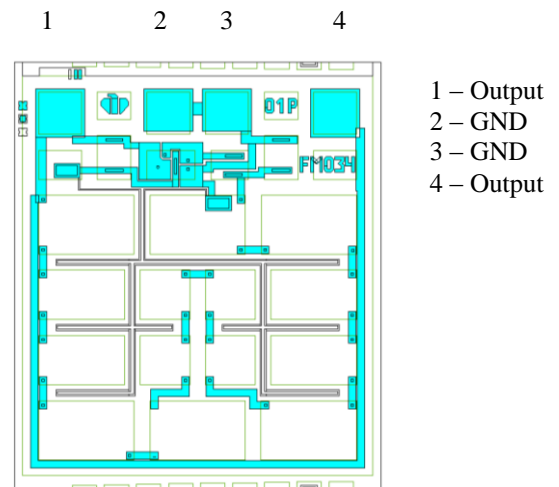
FM034MP.01 chip is fabricated using Silicon Bipolar process technology. The chip is designed to be used in MOS-relay.  
 New monolith polysilicon structure.  
 No delamination at high temperatures.

### Features

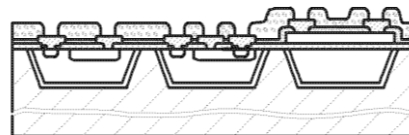
- 14 photodiodes
- Thyristor discharge circuit
- Contact pad's material - Aluminium
- Chip size  $1.2 \times 1.4 \pm 0.1$  mm
- Chip thickness  $0.32 \pm 0.02$  mm

### Absolute maximum ratings

Storage temperature	- 65 °C to 150 °C
Operating Junction Temperature	- 55 °C to 125 °C



Cross section view



### Electrical characteristics (T = 25 °C)

Parameter	Symbol	Unit	Min.	Typ.	Max.	Condition
Open Circuit Voltage	V <sub>OC</sub>	V	7.0	7.8	-	1
Short Circuit Current	I <sub>SC</sub>	μA	3.4	4.2	-	1
Output Voltage	V <sub>OUT</sub>	V	-	-	0.9	2
Discharge Resistor	R <sub>DIS</sub>	MOhm	5.0	-	25.0	
Turn-On Time	T <sub>ON</sub>	ms	-	1.0	-	C <sub>L</sub> = 250 pF
Turn-Off Time	T <sub>ON</sub>	ms	-	0.2	-	C <sub>L</sub> = 250 pF

1 – Light source with peak wavelength  $\lambda = 850 \pm 20$  nm that provides surface irradiance  $E_e = 20$  mWt/cm<sup>2</sup>  
 2 – No light. I<sub>F</sub> = 100 μA